



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SJ104311
(DRAWING NO.)

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	10.Apr.2006	059849	形状変更(インシュレータ) REVISED FORM(INSULATOR)		K.HISAMATSU	M.SUZUKI	H.AMEMIYA
3	21.Apr.2006	059965	誤記訂正 CORRECT AN ERROR		K.HISAMATSU	<i>M. Suzuki</i>	K.HISATOMI

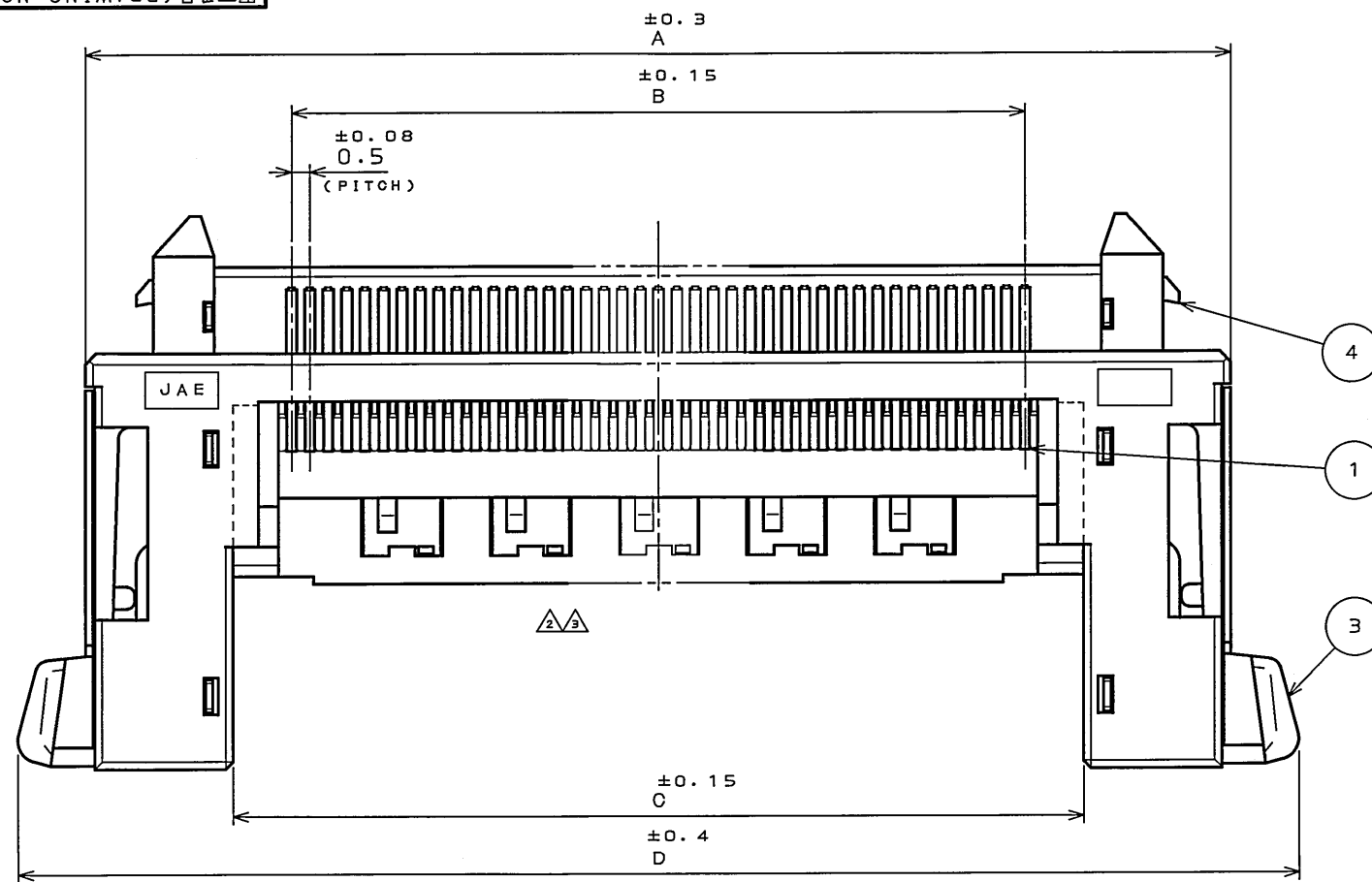


TABLE 1

DIMENSION NO. OF CONTACT(S)	A	B	C	D
21	21.25	10.0	13.2	24.95
31	26.25	15.0	18.2	29.95
41	31.25	20.0	23.2	34.95
51	36.25	25.0	28.2	39.95

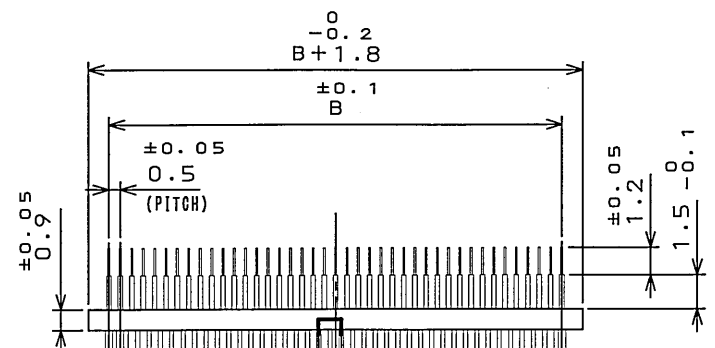
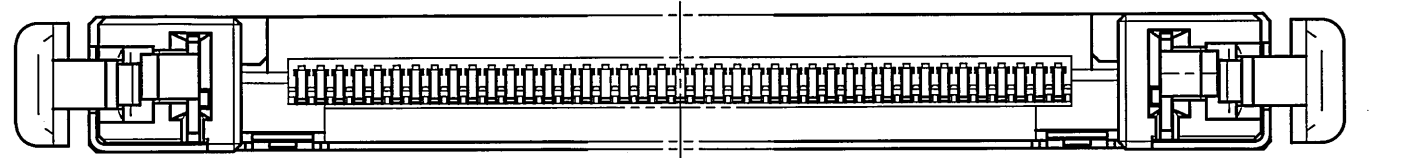
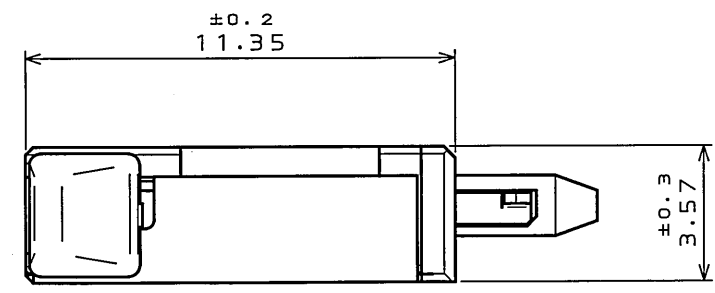
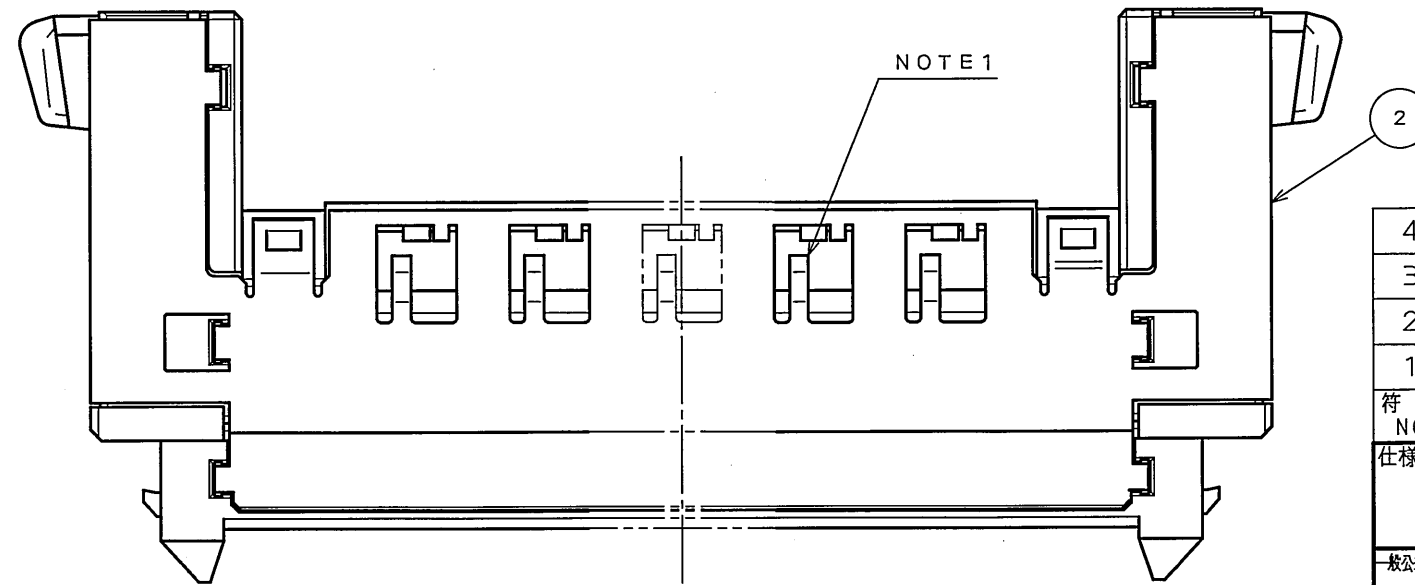
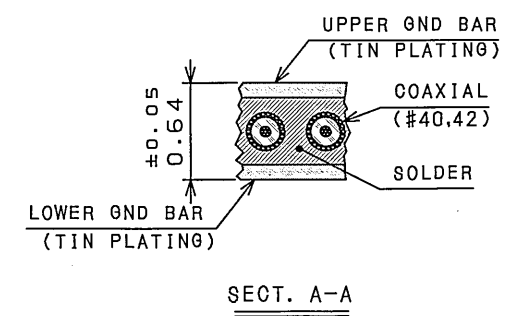


TABLE 2

CONTACT AREA 接触部	SOLDERING AREA 端子部
GOLD OVER NICKEL Ni上Au	TIN OVER NICKEL Ni上Sn



CABLE ASSEMBLED CONDITION(REF.)
ケーブル結線状態図(参考)



符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	LOCK SPRING ロックスプリング	2	STAINLESS STEEL ステンレス		
3	INSULATOR インシュレータ	1	HEAT RESISTING PLASTIC 耐熱性プラスチック		UL94V-0
2	BASE SHELL ベースシェル	1	COPPER ALLOY 銅合金	TIN PLATING Snメッキ	
1	CONTACT コンタクト	N	COPPER ALLOY 銅合金	TABLE1	

仕様書(SPECIFICATION)	第1版(ORIGINAL DATE) 2.Aug.2005	尺度(SCALE) 5:1	シリーズ(SERIES) FI-R	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
製図 DR.	担当 CHK. K.HISAMATSU	名称(TITLE) FI-RE**CL	査閲 APPD. M.SUZUKI	
公差差(GENERAL TOLERANCE)	承認 APPD. K.HISATOMI	質量(MASS)		図面番号(DRAWING NO.) SJ104311
寸法(DIMENSION)	角度(ANGLES)			版数 (REV.) 3

NOTE1. HAND SOLDER BOTH SHELL CONNECTING SHARD AND GROUND BAR.
注1. シェルの接続片とグラウンドバーを半田付けしてください。

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